

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
1	BRS	L1	1	flexible with substrate with flip adj chip and electrode with pierc\$4 and protective and resin with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 18:28			
2	BRS	L2	1	flexible with substrate with flip adj chip and (electrode or contact) with pierc\$4 and protective and resin with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 17:25			
3	BRS	L3	1	flexible with substrate with flip adj chip and pierc\$4 and protective and resin with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 17:24			
4	BRS	L4	3	flexible with substrate with flip adj chip and (electrode or contact) and protective and resin with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 17:26			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
5	BRS	L5	3	flexible with substrate with flip adj chip and protective and resin with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 17:26			
6	BRS	L6	17	flexible with substrate with flip adj chip and protect\$4 and resin with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 17:37			
7	IS&R	L7	2	("6388339").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 17:33			
8	BRS	L8	5	("4643526" "6039896" "6108210" "6265782").PN. OR ("6388339").URP N.	US-PGPUB; USPAT; USOCR	2005/11/27 17:34			
9	BRS	L9	1	2001- 410700.NRAN.	DERWENT	2005/11/27 17:35			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
10	BRS	L11	30	flexible with substrate with chip and protect\$4 and resin with seal\$4 and (under adj fill\$4 or underfill\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 17:38			
11	BRS	L12	27	("5155661" "5616958").PN. OR ("5777386").URP N.	US-PGPUB; USPAT; USOCR	2005/11/27 18:08			
12	BRS	L13	59	("4372037" "4396936" "4574330" "4941067" "5019941" "5075759" "5172303" "5280409" "5285352" "5352926" "5381039").PN. OR ("5616958").URP N.	US-PGPUB; USPAT; USOCR	2005/11/27 18:12			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
13	BRS	L14	14	("4705360" "4792532" "5450283" "5563446" "5646446" "5811877" "5838061" "6051877").PN. OR ("6392143").URP N.	US-PGPUB; USPAT; USOCR	2005/11/27 18:19			
14	BRS	L15	0	(257/616).ccls. and flexible with substrate with chip and protect\$4 and resin with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 18:21			
15	BRS	L16	86	("257"/\$).ccls. and flexible with substrate with chip and protect\$4 and resin with seal\$4 with (side or peripher\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 19:05			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
16	BRS	L17	9	("257"/\$).ccls. and flexible with substrate with flip near chip and protect\$4 and resin with seal\$4 with (side or peripher\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 18:23			
17	BRS	L18	22	("257"/\$).ccls. and flexible with substrate with flip near chip and protect\$4 and resin with (side or peripher\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 18:25			
18	BRS	L19	189	("257"/\$).ccls. and flexible with substrate with chip and protect\$4 and resin with (side or peripher\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 19:00			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Com men ts	Er ro r De fi ni ti on	Er ro rs
19	BRS	L20	26	("257"/\$).ccls. and flexible with substrate with chip and protect\$4 and resin with (side or peripher\$4) and (under adj fill\$4 or underfill\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 18:27			
20	BRS	L21	1	flexible with substrate with chip and electrode with pierc\$4 and protective and resin with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 18:29			
21	BRS	L23	86	flexible with substrate with chip and (electrode or contact) and protective and resin with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 18:29			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
22	BRS	L24	44	("257"/\$).ccls. and flexible with substrate with chip and (electrode or contact) and protective and resin with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 18:35			
23	BRS	L22	1	flexible with substrate with chip and (electrode or contact) with pierc\$4 and protective and resin with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 18:31			
24	BRS	L25	14	("438"/\$).ccls. and flexible with substrate with chip and (electrode or contact) and protective and resin with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 18:37			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
25	BRS	L26	17	compres\$7 and flexible with substrate with chip and (electrode or contact) and protective and resin with seal\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 18:37			
26	BRS	L31	10	("257"/778).ccl s. and flexible with substrate with chip and protect\$4 and resin with seal\$4 with (side or peripher\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 18:58			
27	BRS	L32	0	("257"/698).ccl s. and flexible with substrate with chip and protect\$4 and resin with seal\$4 with (side or peripher\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 18:58			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Comments	Error Definition	Errors
28	BRS	L28	18	("257"/738).ccls. and flexible with substrate with chip and protect\$4 and resin with seal\$4 with (side or peripher\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 18:59			
29	BRS	L35	18	("257"/\$).ccls. and flexible with substrate with flip near chip and protect\$4 and resin with (side or peripher\$4) and (press\$4 or compress\$4 or forc\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 19:02			
30	BRS	L36	24	flexible with substrate with flip near chip and protect\$4 and resin with (side or peripher\$4) and (press\$4 or compress\$4 or forc\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 19:02			

	Type	L #	Hits	Search Text	DBs	Time Stamp	Co mm en ts	Er ro r De fi ni ti on	Er ro rs
31	BRS	L30	16	("257"/668).ccls. and flexible with substrate with chip and protect\$4 and resin with seal\$4 with (side or peripher\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 19:03			
32	BRS	L27	2	("257"/734).ccls. and flexible with substrate with chip and protect\$4 and resin with seal\$4 with (side or peripher\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 19:04			
33	BRS	L37	86	("257"/\$).ccls. and flexible with substrate with chip and protect\$4 and resin with seal\$4 with (side or peripher\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	2005/11/27 19:05			